

United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

DATE MAILED: 07/26/2005

APPLICATION NO.	FII	LING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/670,434	10/670,434 09/23/2003		Pinghai Hao	TI-35470	2415	
23494	7590	07/26/2005		EXAMINER		
TEXAS INS	STRUME	NTS INCORPO	NGUYEN, KHIEM D			
P O BOX 65	•		ART UNIT	PAPER NUMBER		
DALLAS, TX 75265				ARTONII	PAPER NUMBER	
				2823		

Please find below and/or attached an Office communication concerning this application or proceeding.

	<u></u>	Application No.	Applicant(s)				
		10/670,434	10/670,434 HAO ET AL.				
Office Action Summary		Examiner	Art Unit	Τ.			
		Khiem D. Nguyen	2823				
	he MAILING DATE of this communication		with the correspondence a	ddress			
Period for R				<u>.</u>			
THE MA - Extension after SIX - If the peri - If NO peri - Failure to Any reply	TENED STATUTORY PERIOD FOR RI LING DATE OF THIS COMMUNICATION is of time may be available under the provisions of 37 CF (6) MONTHS from the mailing date of this communication and for reply is specified above is less than thirty (30) days, of for reply is specified above, the maximum statutory pereply within the set or extended period for reply will, by sereceived by the Office later than three months after the retent term adjustment. See 37 CFR 1.704(b).	ON. FR 1.136(a). In no event, however, may n. a reply within the statutory minimum of t eriod will apply and will expire SIX (6) M statute, cause the application to become	a reply be timely filed thirty (30) days will be considered time ONTHS from the mailing date of this ABANDONED (35 U.S.C. § 133).	ely. communication.			
Status	•						
1)⊠ Re	sponsive to communication(s) filed on 1	18 May 2005.					
		This action is non-final.		•			
3)∐ Sir	, — , — , — , — , — , — , — , — , — , —						
clo	sed in accordance with the practice und	ler <i>Ex parte Quayle</i> , 1935 C	.D. 11, 453 O.G. 213.				
Disposition	of Claims						
4)⊠ Cla	aim(s) <u>1-22</u> is/are pending in the applica	ation					
	Of the above claim(s) is/are with						
	aim(s) is/are allowed.						
6)⊠ Cla	nim(s) <u>1-22</u> is/are rejected.						
7) Cla	aim(s) is/are objected to.			(
8)☐ Cla	aim(s) are subject to restriction a	nd/or election requirement.					
Application	Papers						
9)□ The	specification is objected to by the Exar	miner.					
10)⊠ The	The drawing(s) filed on <u>23 September 2003</u> is/are: a)⊠ accepted or b)□ objected to by the Examiner.						
Арі	olicant may not request that any objection to	the drawing(s) be held in abey	ance. See 37 CFR 1.85(a).				
	placement drawing sheet(s) including the co	•	• • •	` '			
11)∐ Th∈	e oath or declaration is objected to by th	e Examiner. Note the attach	ed Office Action or form P	TO-152.			
Priority und	er 35 U.S.C. § 119	•					
a)	nowledgment is made of a claim for for bl. bl. Some * c) None of:		. § 119(a)-(d) or (f).				
1.['Annlinetien Ne				
	Certified copies of the priority docunCopies of the certified copies of the	•		l Stago			
, O.L	application from the International Bu	•		i Stage			
* See	the attached detailed Office action for a	• • • • • • • • • • • • • • • • • • • •	ot received.				
Attachment(s)							
	References Cited (PTO-892)	4) Interview	w Summary (PTO-413)				
2) D Notice of	Draftsperson's Patent Drawing Review (PTO-948	Paper N	o(s)/Mail Date				
	on Disclosure Statement(s) (PTO-1449 or PTO/SI (s)/Mail Date	5) Notice of Other:	f Informal Patent Application (PT 	U-152)			

Art Unit: 2823

DETAILED ACTION

New Grounds of Rejection

Claim Rejections - 35 USC § 102

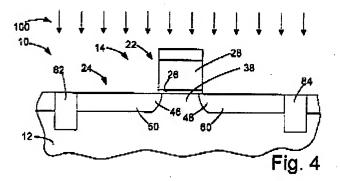
The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

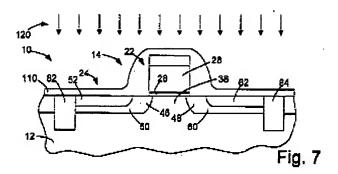
Claims 1-22 are rejected under 35 U.S.C. 102(b) as being anticipated by Fisher (U.S. Patent 6,391,733).

In re claim 1, <u>Fisher</u> discloses a method for fabricating a transistor structure, comprising the steps of: providing a substrate 12 and forming a lightly doped drain (LDD) region 46, 48 in the substrate 12 (FIG. 4);

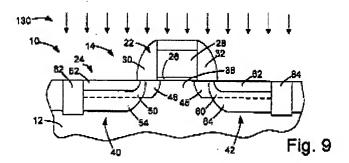


implanting a first dopant **100** has a lower dopant concentration (10¹²-10¹⁵ atoms/cm²) than that of the associated **120** LDD region **46,48** (1x 10¹²- 1x10¹⁶ atoms/cm²) into the lightly doped drain (LDD) region **46, 48** to a depth less than a LDD junction depth (col. 4, line 45 to col. 5, line 34 and FIG. 7); and

Art Unit: 2823



implanting a second dopant 130 into the substrate 12 beyond the LDD junction depth to form a source/drain region 54,64, the implantation of the second dopant overpowering $(5x10^{14}-1x10^{16})$ atoms/cm² a substantial portion of the first dopant to define a floating region 52, 62 of the first dopant within the LDD region 46, 48 (col. 5, lines 43-54 and FIG. 9).



In re claim 2, <u>Fisher</u> discloses that the floating region further comprising a floating ring 52, 62, substantially self-aligned with an edge of a gate 28 of the transistor structure 14 (col. 5, lines 19-34 and FIG. 9).

In re claim 3, <u>Fisher</u> discloses that the method of claim 1, further comprising forming the LDD region 46, 48 by implanting a dose $120 (1x10^{12}-1x10^{16} \text{ atoms/cm}^2)$ of an LDD dopant that is greater than a dose of the first dopant $100 (10^{12}-10^{15} \text{ atoms/cm}^2)$ (col. 4, line 45 to col. 5, line 34 and FIGS. 4 and 7).

Art Unit: 2823

In re claim 4, <u>Fisher</u> discloses that the dose of the first dopant 100 being about twenty-percent or less of the dose of the LDD dopant 120 (col. 4, line 45 to col. 5, line 34 and FIGS. 4 and 7).

In re claim 5, it is well-known to one of ordinary skill in the art at the time of the invention was made that the at least one of the implantation of the first dopant and the implantation of the LDD dopant employing tilted angle implants to enhance an amount of overlap between a gate structure of the transistor structure and the LDD region.

In re claim 6, <u>Fisher</u> discloses that the dose of the second dopant 130 $(5x10^{14}-1x10^{16} \text{ atoms/cm}^2)$ being greater than the dose of the LDD dopant 120 $(1x10^{12}-1x10^{16} \text{ atoms/cm}^2)$ (col. 5, lines 19-54 and FIGS. 7 and 9).

In re claim 7, **Fisher** discloses that the implantation of the LDD dopant further comprising implanting a dose of n-type dopant in the range from about $(1x10^{12}-1x10^{16}$ atoms/cm²), and the implantation of the first dopant **100** further comprising implanting a dose in a range from about $(10^{12}-10^{15} \text{ atoms/cm}^2)$ of a p-type dopant (col. 4, line 45 to col. 5, line 34).

In re claim 8, <u>Fisher</u> discloses that the transistor structure is a complimentary metal oxide semiconductor (CMOS) structure that includes a gate 28 having a side edge portion, the floating region 52, 62 being substantially aligned with the side edge portion of the gate 28 (FIG. 9).

In re claim 9, <u>Fisher</u> discloses that the CMOS structure is an n-channel CMOS structure, the first dopant 100 forming a shallow region in the LDD region that comprises a p-type dopant (FIG. 4).

Art Unit: 2823

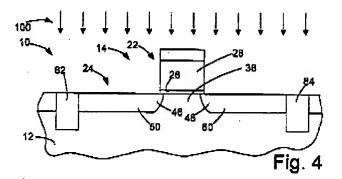
In re claim 10, <u>Fisher</u> discloses that the first dopant 100 comprises boron (B), and the floating region 52, 62 further comprises a boron floating ring, substantially aligned with side edge portion of the gate 28 (col. 4, lines 45-53 and FIGS. 4 and 9).

In re claim 11, <u>Fisher</u> discloses that the CMOS structure is a p-channel CMOS structure, the first dopant 100 defining a shallow region that comprises an n-type dopant (FIGS. 4 and 9).

In re claim 12, <u>Fisher</u> discloses that the method of claim 1, further comprising: forming a gate structure 28 above the substrate 12, the LDD region 46, 48 and the source/drain region 54, 64 being formed in the substrate 12 generally around the gate structure 28 the gate structure overlapping at least a substantial portion of the LDD region 46, 48 and the floating ring 52, 62 being substantially aligned with an edge of the gate structure 28 (FIG. 9).

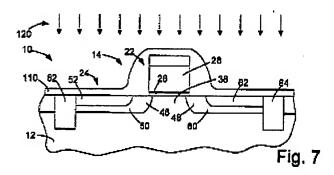
In re claim 13, <u>Fisher</u> discloses a method for fabricating a CMOS transistor device, comprising the steps of forming a gate structure 28 on a substrate 12, the gate structure 28 having a side edge;

forming a lightly doped drain (LDD) region 46, 48 in the substrate 12 laterally of a channel region 38 and extending beneath the gate structure (FIG. 4);

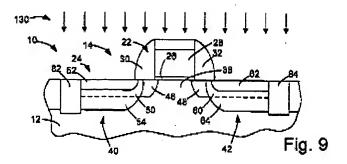


Art Unit: 2823

then forming a shallow region $(10^{12}-10^{15} \text{ atoms/cm}^2)$ in the LDD region 46, 48 having a lower concentration than that of the associated LDD region $(1x10^{12}-1x10^{16} \text{ atoms/cm}^2)$ that extends into the substrate 12 to a depth that is less than an LDD junction depth and spaced from the channel region (col. 4, line 45 to col. 5, line 34 and FIGS. 4 and 7); and



forming a source/drain region **54,64**, the formation of the source/drain region resulting in forming a floating structure **52, 62** from the shallow region that is located in the LDD region **46, 48** and generally aligned with the side edge of the gate structure 28 (col. 5, lines 43-54 and FIG. 9).



In re claim 14, <u>Fisher</u> discloses that the LDD region 46, 48 being formed with a dose $(1x10^{12}-1x10^{16} \text{ atoms/cm}^2)$ of a dopant that is greater than a dose of a dopant utilized

Art Unit: 2823

to form the shallow region (10¹²-10¹⁵ atoms/cm²) (col. 4, line 45 to col. 5, line 34 and FIGS. 4 and 7).

In re claim 15, <u>Fisher</u> discloses that the dose of the dopant 100 that is utilized to form the shallow region is at least approximately twenty-percent less than the dose of the dopant 120 that is utilized to form the LDD region 120 (col. 4, line 45 to col. 5, line 34 and FIGS. 4 and 7).

In re claim 16, <u>Fisher</u> discloses the formation of the LDD region 46, 48 further comprising implanting a dose 120 of n-type dopant in a range from about $(1x10^{12}-1x10^{16}$ atoms/cm²), and the formation of the shallow region further comprising implanting a dose 100 in a range $(10^{12}-10^{15} \text{ atoms/cm}^2)$ (col. 4, line 45 to col. 5, line 34 and FIGS. 4 and 7).

In re claim 17, it is well-known to one of ordinary skill in the art at the time of the invention was made that the at least one of the implantation of the formation of the LDD region and the formation of the shallow region further comprising employing tilted angle implants to increase an amount of overlap beneath the gate structure.

In re claim 18, <u>Fisher</u> discloses that the formation of the source/drain region 54, 64 being implemented with a dose of a dopant $(5x10^{14}-1x10^{16} \text{ atoms/cm}^2)$ that is greater than a dose of a dopant utilized to form each of the LDD region 120 $(1x10^{12}-1x10^{16} \text{ atoms/cm}^2)$ and the shallow region (col. 5, lines 19-54).

In re claim 19, <u>Fisher</u> discloses that the CMOS structure is an n-channel CMOS structure, the shallow region comprising a p-type dopant (col. 4, line 45 to col. 5, line 54).

Art Unit: 2823

In re claim 20, <u>Fisher</u> discloses that the shallow region comprising boron (B), the floating structure **52**, **62** comprising a boron floating ring **52**, **62** substantially aligned with the side edge of the gate structure **28** (col. 4, lines 45-53 and FIGS. 4 and 9).

Page 8

In re claim 21, <u>Fisher</u> discloses that the CMOS structure is a p-channel CMOS structure, the shallow region comprising an n-type dopant (col. 4, line 45 to col. 5, line 54).

In re claim 22, <u>Fisher</u> discloses a transistor structure formed according to the method of claim 13 (FIG. 9).

Response to Applicant's Amendment and Arguments

Applicant's arguments with respect to claims 1-22 have been considered but are moot in view of the new ground(s) of rejection.

Applicants contend that Claim 1 requires, among other steps, the step of implanting a first dopant that has a lower concentration than that of the associated LDD region into the lightly doped drain (LDD) region to a depth less than a LDD junction depth.

Applicants stated that no such step is taught or suggested by Mandelman either alone in the combination as claimed.

In response to Applicants' contention that Mandelman does not teach or suggest the step of implanting a first dopant that has a lower concentration than that of the associated LDD region into the lightly doped drain (LDD) region to a depth less than a LDD junction depth.

Examiner respectfully submits that Applicants' argument is moot since

Applicant's amendment necessitated the new ground(s) of rejection presented in this

Art Unit: 2823

Office action. The newly discovered reference to Fisher (U.S. Patent 6,391,733) applied under 35 U.S.C. 102(b) rejection teaches the Applicants' claimed invention (Applicants are directed to page 2, 2nd paragraph to page 3, 1st paragraph presented in this Office Action) where Fisher discloses implanting a first dopant 100 has a lower dopant concentration (10¹²-10¹⁵ atoms/cm²) than that of the associated 120 LDD region 46,48 (1x 10¹²- 1x10¹⁶ atoms/cm²) into the lightly doped drain (LDD) region 46, 48 to a depth less than a LDD junction depth (col. 4, line 45 to col. 5, line 34 and FIG. 7); and implanting a second dopant 130 into the substrate 12 beyond the LDD junction depth to form a source/drain region 54,64, the implantation of the second dopant overpowering (5x10¹⁴-1x10¹⁶) atoms/cm² a substantial portion of the first dopant to define a floating region 52, 62 of the first dopant within the LDD region 46, 48 (col. 5, lines 43-54 and FIG. 9).

For this reason, Examiner holds the rejection proper.

Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a). A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the

advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Khiem D. Nguyen whose telephone number is (571) 272-1865. The examiner can normally be reached on Monday-Friday (8:30 AM - 5:30 PM).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Matthew S. Smith can be reached on (571) 272-1907. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

K.N. July 22nd, 2005

W. DAVID COLEMAN
PRIMARY EXAMINER